AMENDMENTS TO THE SPECIFICATION

On page 1, please replace paragraphs [0001]-[0004] with the following rewritten paragraphs:

[0001] This application is a continuation-in-part of U.S. Application Serial No. 10/391,924, ~~(NT-291)~~ filed Mar. 18, 2003, ~~and claims priority from Provisional Application Ser. No. 60/425,694 (NT-281P) filed Nov. 12, 2002, all~~ incorporated herein by reference.

[0002] This application is also a continuation-in-part of U.S. Application Serial No. 10/093,185, filed Mar. 5, 2002, ~~(NT-003C)~~ now U.S. Patent No. 6,958,114, which is a continuation of U.S. Application Serial No. 09/877,335, filed Jun. 7, 2001 ~~(NT-003D)~~, now U.S. Patent No. 6,471,847, which is a divisional of U.S. Application Serial No. 09/283,024, filed Mar. 30, 1999 ~~(NT-003)~~, now U.S. Patent No. 6,251,235, all incorporated herein by reference.

[0003] This application is also a continuation-in-part of U.S. Application Serial No. 10/459,321, ~~(NT-105C4)~~ filed Jun. 10, 2003, which is a continuation of U.S. Application Serial No. 10/302,213, filed Nov. 22, 2002, which is a continuation of U.S. Application Serial No. 09/685,934, filed Oct. 11, 2000 ~~(NT-105)~~, now U.S. Patent No. 6,497,800, which claims ~~claiming~~ priority to U.S. Provisional Serial No. 60/190,023, filed Mar. 17, 2000, all incorporated herein by reference.

[0004] This application is also a continuation-in-part of U.S. Application Serial No. 10/238,665, filed Sep. 9, 2002 ~~(NT-001C1)~~, now U.S. Patent No. 6,902,659, which is a continuation of U.S. Application Serial No. 09/607,567, filed Jun. 29, 2000, ~~(NT-001D),~~ now U.S. Patent No. 6,676,822, which is a divisional of U.S. Application Serial No. 09/201,929, filed Dec. 1, 1998, ~~(NT-001)~~ now U.S. Patent No. 6,176,992, all incorporated herein by reference.

On pages 3 and 4, please replace paragraphs [0012] with the following rewritten paragraph:

[0012] There are several patents and patent applications describing the electroetching process carried out with the assistance of the mechanical action provided by a pad or WSID. Details of such processes are given in the following patents and patent applications:[[;]] U.S. [[Pat.]] Patent No. 6,402,925; U.S. ~~patent application Ser.~~ Application

Serial No. 10/238,665, entitled "Method and ~~apparatus for electroplating and electropolishing,~~ Apparatus for Electro-Chemical Mechanical Deposition," filed Sep. [[20]] 9, 2002, now U.S. Patent No. 6,902,659; U.S. ~~patent application Ser.~~ Application Serial No. 09/671,800, entitled[[,]] ~~Method to minimize/eliminate metal coating over the top surface of a patterned substrate and layer structure made thereby,~~ "Process to Minimize and/or Eliminate Conductive Material Coating over the Top Surface of a Patterned Substrate and Layer Structure Made Thereby," filed Sep. 28, 2000; U.S. ~~patent application Ser.~~ Application Serial No. 09/841,622, entitled "Electroetching ~~system and method,~~ Process and System," filed Apr. 23, 2001, now U.S. Patent No. 6,852,630; U.S. ~~patent application Ser.~~ Application Serial No.10/201,604, entitled[[,]] ~~Multi-step electrodeposition process,~~ "Multi Step Electrodeposition Process for Reducing Defects and Minimizing Film Thickness," filed Jul. 22, 2002, now U.S. Patent No. 6,946,066; and U.S. Provisional Application Ser. No. 60/362,513, filed Sep. 1, 2003, entitled[[,]] "Method and Apparatus for Planar Material Removal ~~technique using multi-phase process environment,~~ Technique Using Multi-Phase Process Environment," filed Mar. 6, 2002~~, U.S. application Ser. No. 10/238,665, entitled "Method and apparatus for electroplating and electropolishing, filed Sep. 20, 2002 all commonly owned by the assignee of the present invention~~.

On pages 4 and 5, please replace paragraphs [0015] with the following rewritten paragraph:

[0015] Contact designs that allow full-face electrodeposition or electroetching have been described in the following U.S. patent applications: U.S. ~~patent application Ser.~~ Application Serial No. 09/685,934, entitled[[,]] ~~Making electrical contact to the surface of a workpiece during metal plating,~~ "Device Providing Electrical Contact to the Surface of a Semiconductor Workpiece During Metal Plating," filed Oct. 11, 2000, now U.S. Patent No. 6,497,800; U.S. ~~patent application Ser.~~ Application Serial No. 09/735,546, entitled[[,]] ~~Method of electrical contact to wafer frontal side for electrochemical plating,~~ "Method of and Apparatus for Making Electrical Contact to Wafer Surface for Full-Face Electroplating or Electropolishing," filed Dec. 14, 2000, now U.S. Patent No. 6,482,307; and[[,]] U.S. ~~patent application Ser.~~ Application Serial No. 09/760,757, entitled[[,]] "Method and ~~apparatus for electrodeposition of uniform film on substrate,~~ Apparatus for Electrodeposition of Uniform Film with Minimal Edge

Exclusion on Substrate," filed Jan. 17, 2001, now U.S. Patent No. 6,610,190, all commonly owned by the assignee of the present invention. As described in these applications, one method of making electrical contact to the workpiece surface involves physically touching the conductive surface of the workpiece by conductive contact elements, such as wires, fingers, springs, rollers, brushes etc., and establishing a relative motion between the contact elements and the wafer surface so that different sections of the wafer surface is physically and electrically contacted at different times. In another method, electrical contact to the workpiece surface is achieved without physically touching the wafer by the conductive contact elements. Either way, electrical contacts may be made substantially all over the surface of the wafer or only at the edge region of the wafer.